FEAST

CERN

Radiation tolerant 10W Synchronous Step-Down Buck DC/DC converter

Features

- Input voltage range 5 to 12V
- Continuous 4A load capability
- Integrated Power N-channel MOSFETs
- Adjustable switching frequency 1-3MHz
- Synchronous Buck topology with continuous mode operation
- High bandwidth feedback loop (150KHz) for good transient performance
- Over-Current protection
- Under-voltage lockup
- Over-Temperature protection
- Power Good output
- Enable Input
- Selectable Power Transistor size (5/5th or 2/5th) for improved efficiency at small loads (<600mA)
- Radiation tolerant: TID up to >200Mrad(Si), displacement damage up to 5-8·10¹⁴n/cm² (1MeV-equivalent), no destructive SEEs up to >30MeVcm²mg⁻¹, SEFI (reset) cross-section in a 230MeV proton beam ~ 2.8·10⁻¹³ cm²

Applications

Point Of Load in distributed power systems where either radiation tolerance or magnetic field tolerance, or both, are required

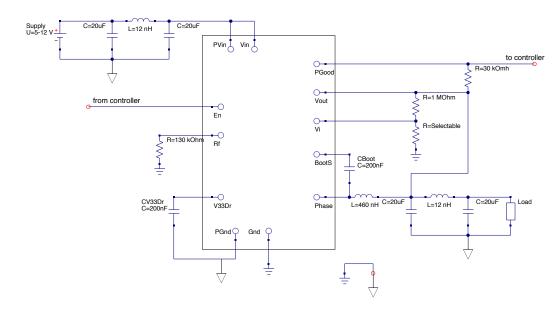
Description

FEAST is a single-phase synchronous buck converter developed to provide an efficient solution for the distribution of power in High Energy Physics experiments. As such, it has

been designed for flawless functionality in a harsh radiation and magnetic field environment. The selection of an appropriate CMOS technology, coupled to the systematic use of Radiation Hardness By Design (RHBD) techniques, makes the converter capable of continuous operation up to more than 200Mrad(Si) total ionizing dose and an integrated particle fluence of 5-8·10¹⁴n/cm² (1MeV-equivalent). Single Event Effects resilience has been built-in, and the circuit has been tested free of destructive SEEs with heavy ions up to an LET of 30MeVcm²mg⁻¹ at normal and 60° incidence (no data available for higher LETs). Moreover, a large number of samples (31) have been exposed to a 230MeV proton beam, showing sensitivity to Single Event Functional Interrupt (SEFI) that manifests as short (500us) resets with a cross-section of about 2.8·10⁻¹³ cm². The origin of this sensitivity has been investigated with pulsed laser tests, and hopefully corrected in a new version of the ASIC that will be available in May 2014. FEAST has been designed for operation in a strong magnetic field in excess of 40,000 Gauss, and has been optimized for air-core inductors of 400-500nH; to be compatible with these small coil values, its switching operation is in the 1-3MHz range (1.5-2MHz for maximum efficiency).

The monolithic construction of FEAST, with the integration of the power train and the bootstrap diode with the controller, makes the converter a space-efficient solution to provide POL regulation from a 5-12V supply rail. Its protection features include Over-Current, Over-Temperature and Under-Voltage to improve system-level security in the event of fault conditions.

Typical application

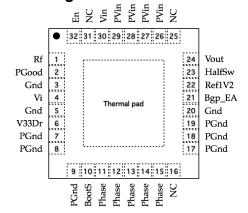


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Absolute Maximum Ratings

Power Input Voltage PVin	0.3V to +12.0V
Control Input Voltage Vin	0.3V to +12.0V
Bootstrap Voltage BootS	0.3 to PVin+3.6V
Phase Voltage0.3 V to Vin (DC), -2 to	o 13.5 V (AC, 10ns)
Phase to BootS Voltage	0.3V to +3.6V
Driver Voltage, V33Dr	0.3V to +3.6V
Feedback input Voltage of the E/A Vi	0.3V to +3.6V
Frequency selector Rf	0.3V to +3.6V
Power transistor size toggle HalfSw	0.3V to +3.6V
Reference voltage toggle Ref1V2	0.3V to +3.6V
Converter Enable En	0.3V to +3.6V
Power good PGood	0.3V to +3.6V
Output Voltage Vout	0.3V to +6.0V
Current in PGood pin (when PGood is neg	gated)50uA

Pin Configuration



Top view - 32-lead plastic QFN (5x5 mm) Thermal pad must be soldered to PCB PGND

Pin Function

Rf (Pin 1): Frequency Selector. A resistor placed between this Pin and the board GND determines the switching frequency of the converter as illustrated in the following table. The recommended range for best performance is 1.5-2 MHz.

Resistance	Frequency
270K	1.03
200K	1.35
180K	1.48
160K	1.65
130K	1.99
100K	2.51
82K	2.98

PGood (Pin2): Power Good flag. This output pin comes from an open-drain NMOS transistor that is conductive when the converter is not regulating the output voltage. It requires a pull-up resistor to the appropriate user-required voltage. It is recommended to obtain this voltage from Vout, either with a simple pull-up or with a voltage divider (in all circumstance, the PGood signal must not exceed 3.6V). The value of the pull-up resistor determines the current in the open-drain NMOS, which should be limited below 50uA. PGood is asserted (NMOS off) during normal operation, while it is negated (NMOS on) in disable mode, during restart, in case of under-voltage or over-temperature, and when the output voltage is outside a regulation window approximately $\pm 6.5\%$ around the selected Vout.

Gnd (Pin3, 5, 20): Ground of the control electronics of the converter. It must be connected to the PCB ground plane possibly in a location remote to the power current loop in the same plane.

Vi (Pin 4): Input voltage of the Error Amplifier. The compensation network is integrated on-chip and ensures a bandwidth of about 150kHz, but the DC regulation voltage Vout is selected by the addition of 2 resistors building a voltage divider between Vout and gnd. Vi is connected between the 2 resistors and the resulting

voltage is compared to the internal reference voltage (1.2 or 0.6V depending on the value of the toggle Pin Ref1V2). The resistor between Vout and Vi must have a value of $1M\Omega$, while the one between Vi and gnd is selectable (no resistor makes Vout = Vref).

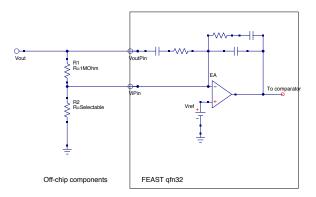


Figure 1: Configuring the output voltage.

V33Dr (Pin6): Voltage supply for the drivers of the power transistors. Although the regulator providing the 3.3V to the drivers is integrated, the large gate capacitance of the power switches requires a hefty charge storage element capable of providing quickly all the required transient current. This can not be achieved by on-chip capacitor, and an external capacitor of 220nF, positioned as close to the V33Dr pin as possible and directly connected to the PGnd (on the top PCB layer), is required.

PGnd (Pin 7, 8, 9, 17, 18, 19): Power Ground. This is the gnd of the power train and drivers, where large current transients are flowing. All PGnd pins must be connected to a large power plane under the qfn32, itself soldered to the Thermal Pad of the package, and connected to the PCB gnd plane by a large number of vias.

BootS (Pin 10): BootStrap capacitor voltage. FEAST uses 2 NMOS transistors in the power train, and the High Side (HS) switch requires a BootStrap circuit, which is embedded, for correct

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gate driving (the gate has to be connected to Phase for turn-off and to Phase+3.3V for turn-on). Given the large size of the HS power switch, an off-chip capacitor is required to provide the transient current to the HS drivers during switching. This capacitor, of 220nF, must be positioned between Phase and BootS pins, as close as possible to the qfn32 package.

Bgp_EA (Pin 21): This pin must be left floating. The reference voltage to the Error Amplifier was made observable at this pin exclusively for test purposes. Connecting this pin might alter the noise performance.

Ref1V2 (Pin 22): Toggle of the on-chip reference voltage. If this pin is connected to gnd, FEAST switches to the use of the 1.2V reference, otherwise (Pin floating) it uses the 0.6V reference. It is strongly recommended to leave it floating and use the 0.6V reference, since this is the only configuration in the upgraded version of the ASIC (with improved SEE tolerance).

HalfSW (Pin 23): Toggle controlling the size of the power train transistors. If this pin is connected to gnd, only $2/5^{th}$ of the integrated power switches are used, decreasing the power required

to charge their large gate capacitance (increasing however their onresistance). In this configuration, efficiency increases for light loads – below about 600mA. For larger loads, leave the pin floating for higher efficiency and reliability.

Vout (Pin 24): Regulated output voltage. This is an input pin bringing the Vout back to the converter's feedback circuit. It must be connected as specified in the description of Pin 4 (Vi).

PVin (Pin 26, 27, 28, 29): Power Input Voltage. Input voltage of the power switches and drivers, where large current transients are flowing. Large input capacitances must be connected between this pin and PGnd as close to the package as possible (see board design recommendations later on).

En (Pin 32): Enable input. FEAST in normally disabled and requires a voltage above 850mV applied to this pin to be enabled and start operation. This voltage value has been chosen to make the pin compatible with control from almost any CMOS logic controller between 0.9 and 3.3V.

Recommended Operating Conditions

Description	Min	Max	Unit
Input voltage - PVin, Vin	5	11	V
Output voltage - Vout	1.2	5	V
Conversion ratio - Vout/Vin	2	10	
Output current – Iout (supposes efficient cooling of PCB ground plane)	0	4	A
Output power – Pout (supposes efficient cooling of PCB ground plane)	0	10	W
Switching frequency	1.5	2	MHz
Cooling plate temperature (temperature of the PCB ground plane that has to be attached to a cooling plate)	-40	30	°C
Output current above which HalfSw should be left floating for higher efficiency and reliability	600	800	mA
Inductor value	400	500	nН
Enable voltage		3.3	V
Power Good voltage		3.3	V

Electrical Specifications

SYMBOL	PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNITS
Power	Power					
PVin, Vin	Input voltage supply range		5	-	12	V
Iin	Input current for control electronics (via Vin pin)	En pin low, converter disabled	-	2	-	mA
Iout (note1)	Output current	f=1.8MHz, L=460nH, package thermal pad soldered to PCB, PCB in air	-	-	1	A
		f=1.8MHz, L=460nH, good thermal contact with cooling plate at 18°C	-	-	4	A
Pout (note1)	Output power	f=1.8MHz, L=460nH, package thermal pad soldered to PCB, PCB in air	-	-	2	W
		f=1.8MHz, L=460nH, good thermal contact with cooling plate at 18°C	-	-	10	W

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PWM						
DMax	Maximum Duty Cycle		-	100	-	%
DMin	Minimum Duty Cycle	nimum Duty Cycle				%
Error Amplif	iier					
DCG	DC Gain	CL = 1pF at VF Pin	-	90	-	dB
UGBW	Unity Gain-Bandwidth	CL = 1pF at VF Pin	-	20	-	MHz
SR	Slew Rate	CL = 1pF at VF Pin	-	10	-	V/µs
Under-Voltag	ge Lockout					
VinStartTh	Vin start threshold	Vin rising trip level (note2)	-	4.63	-	V
VinStopTh	Vin stop threshold	Vin falling trip level (note2)	-	4.36	-	V
Enable				-11		1
EnStartTh	Enable start threshold	Enable rising trip level (note2)	-	810	-	mV
EnStopTh	Enable stop threshold	Enable falling trip level (note2)	-	730	-	mV
EnSerRes	Enable pin series resistance (to limit current through ESD when FEAST is not powered)	(to limit current through ESD when FEAST is not				kΩ
Protections						
OCPpk	Over Current Protection peak level	Vin=10V, Vout=2.5V, f=1.8MHz, L=410nH, Tcoolingpad≈18°C, (note3)	-	8.5	-	A
OCPavg	Over Current Protection average output current level	Vin=10V, Vout=2.5V, f=1.8MHz, L=410nH, Tcoolingpad≈18°C, (note2, note4)	-	6.1		A
OTPStartTh	Over Temperature Protection start threshold	Tj rising trip level, (note2)	-	103	-	°C
OTPStopTh	Over Temperature Protection stop threshold	Tj falling trip level, (note2)	-	73	-	°C
Soft Start						
SSt	Duration of the Soft Start procedure to reach regulation at nominal Vout	Vin=10V, Vout=2.5V, f=1.8MHz, L=410nH, Tcoolingpad≈18°C, (note2, note5)		470		us
Power Good						
OV	Output Over Voltage PGood upper threshold			+6.5		%
UV	Output Under Voltage PGood lower threshold			-6.5		%

Notes

- *Note 1*: Max rated output current only allowed if max output power is not exceeded.
- Note 2: Average value taken from measurements on 10 samples from the production run.
- Note 3: This value has not been measured precisely and is reported as approximate indication of the peak current detection for OCP. The peak value does not have relevant dependence on Vin and Vout.
- Note 4: The OCP uses a peak detector, hence the average output current for OCP detection depends on the input and output voltages. Approximate current values measured for an individual sample for Vin=10V and different Vout are: 6A (5V), 6.2A (3.3V), 6.2A (2.5V), 6.6A (1.8V), >6.8A (1.5V).
- Note 5: The duration of the Soft Start does not have a relevant dependence on Vin and Vout.

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Block Diagram

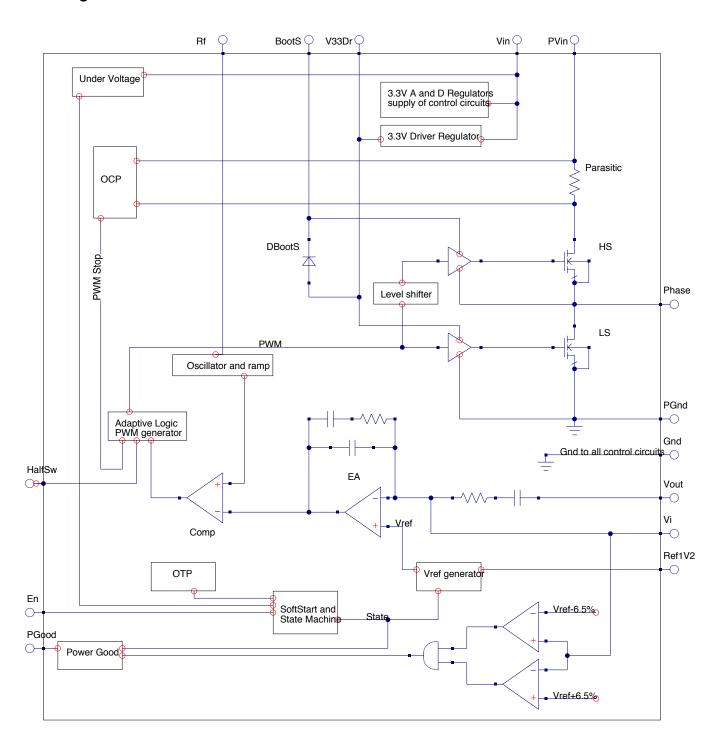


Figure 2: Block diagram of the FEAST ASIC.

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Operation

FEAST is a DCDC converter designed specifically for application in the high radiation and magnetic field of experiments in High Energy Physics. Radiation tolerance is a particularly difficult target for a DCDC converter, and its achievement required to compromise on other performances typically important in similar components in the commercial marketplace. The typical application at steady large load current with power provided from a remote supply (not from a battery) implies very relaxed requirements on quiescent current, while a fast feedback loop is at premium for some detectors where current consumption might have an instantaneous threefold increase.

Designed to be embedded in a custom DCDC module and distributed in this form to users, FEAST has not been designed and tested for allowing large freedom in the choice of the external components (capacitors, inductors and resistors). Moreover, its use in an environment very sensitive to conducted and radiated noise in a physics experiments demands large expertise in EMC design since the position and choice of all components has large influence on the final detector performance. It is hence strongly advised not to procure FEAST in its stand-alone packaged form but to use the available full DCDC converter module which has been qualified for class-B conducted noise (CISPR11) and has been shown to be well compatible with integration in very close proximity to the sensitive readout electronics of even the tracker silicon detectors. The module exists in both positive (FEASTMP) and negative (FEASTMN) output voltage versions, and datasheets can be found under the public web page of the DCDC PH-ESE project: http://project-dcdc.web.cern.ch.

Output voltage selection

The output voltage is determined by the choice of the 2 resistors in voltage divider configuration between Vout and gnd (Figure 1). In doing so, it is important to know as precisely as possible the value of the reference voltage to the Error Amplifier. This has been measured on 40 tests points on each production wafer for the 0.6V configuration. The average value over the 6 wafers is 597mV with a standard deviation of 4.4mV (minimum measured: 584mV; maximum measured: 608mV).

Switching frequency

The switching frequency of the converter can be adjusted with one external resistor, which provides the bias current to the embedded oscillator. Although FEAST has been tested as functional over a wide range of frequency (1 to 3.5MHz), best performance is achieved in the range of 1.5-2MHz. At lower frequency, the peakpeak current in the small air-core inductor increases excessively and determines useless losses and possibly an early onset of the OCP. At higher frequency, driving losses increases dramatically and make the efficiency drop very sensibly. While usage at 1.5MHz allows top efficiency, 1.8MHz operation allows for reduced conductive noise and is preferred as default configuration.

Embedded linear regulators

While it can operate from a supply voltage of up to 12V, the control electronics in FEAST requires powering at 3.3V. A number of linear regulators are embedded to provide appropriate voltage to the drivers of the power transistors, to the bandgap and reference current generator, to the analog and to the digital circuitry. With the exception of the voltage regulation for the power transistors' drivers, all storage capacitors required for the regulators are on-chip

and have been sized to ensure steady voltage even during large current surges.

Under-Voltage lockout

The embedded linear regulators need a sufficient level of overvoltage to provide stable 3.3V voltage to the control circuitry. To prevent faulty operation because of lack of appropriate supply to the control electronics, an on-chip comparator only enables operation of the circuit when the input voltage is above about 4.7V (on rising Vin). This comparator has an hysteresis and FEAST is disabled again when, for falling Vin, the input voltage drops below about 4.4V.

Enabling FEAST

The circuit is disabled by default, so it will not start when a sufficient Vin is applied to its input unless the available enable pin (En) has not been asserted by applying a voltage above 850mV. FEAST can hence be turned on-off by a control signal without the need for removing the power to its Vin bus, which makes easy its parallelization on the same supply bus (each FEAST providing regulated power to a different load).

Soft Start procedure

When the converter is enabled a large current is required to charge the output capacitors to the nominal regulated voltage. This current has to be limited to avoid circuit damage. A pre-defined Soft Start (SS) procedure takes care of limiting the inrush current by gently increasing the reference voltage of the EA, the output voltage reaching the nominal value in about 470us in the nominal configuration using the 0.6V bandgap (at the switching frequency of 1.8MHz, this time varying inverse linearly with frequency). Every time the converter is disabled – either by acting on the En pin, by under-voltage lockout, or by OTP detection – it follows a hard-wired sequence to reach the state where it efficiently regulates the output voltage. This sequence is controlled by an embedded 2bits state machine. SS takes place in the third of the 4 states and finishes when the rising reference voltage slightly exceeds the bandgap reference voltage. At this time, the reference to the EA is switched to the steady reference generator (bandgap). It is hence normal to observe a small decreasing voltage step in Vout at the end of the SS procedure.

Power Good flag

The PG output pin is used to signal that FEAST is correctly regulating the output voltage. For easy compatibility with almost any CMOS logic level up to 3.3V, this output is an open drain (of an NMOS transistor). This transistor is normally disabled when the converter is regulating correctly, while it is turned on otherwise: in disabled state (En pin low), in OTP, in reset and when the output voltage is outside a $\pm 6.5\%$ window around nominal. In the absence of Vin, or in under-voltage lockout, power is not provided to the control electronics and the open-drain transistor cannot exert its pull-down function. To avoid PG to rise in this condition it is recommended to use Vout as pull-up voltage (either directly or via a voltage divider). Current in the NMOS pull-down transistor has to be limited below 50uA, so an appropriate pull-up network has to be selected. The absolute maximum voltage on the PG pin is 3.6V.

Over-Temperature Protection (OTP)

A dedicated circuit monitors the on-chip junction temperature and disables FEAST when it reaches about 103°C (the OTP temperatures are not precisely measured since T is not measured on FEAST itself). The OTP has a hysteresis of about 30°C, hence the converter restarts (with SS) when the junction temperature decreases below 73°C. In case of inefficient cooling, it is hence

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possible that the converter cycles between the disabled and enabled states at a frequency dependent on the load and cooling conditions.

Over-Current Protection (OCP)

OCP is integrated as a real peak detector on the current flowing during each cycle in the HS transistor. Current sensing takes place on the parasitic resistance of metal lines bringing the input current from the input pads to the HS transistor. When the instantaneous current exceeds about 8.5A, the PWM is reset and forces the HS to turn off. If the excessive load current condition persists, the on-time of the HS is not determined anymore by the feedback loop (which would require longer on-times to provide more output power) but by the OCP, and as a consequence the output voltage drops. This condition might endure as a steady state, PG being pulled to gnd if the output voltage drop exceeds 6.5% of the nominal. The peak current of 8.5A translates in different average output current depending on the input and output voltage, frequency and inductor value.

Compensation network

The compensation network is fully integrated and determines a typical loop bandwidth of about 150kHz in the recommended operation environment (frequency, voltages, inductor, on-board passives). FEAST is hence capable of quickly adjusting the output voltage in case of output load transients.

Cooling

FEAST is specified for operation up to 10W output power. With an efficiency of 80% in case of large load current and not-cryogenic cooling, this translates in more than 2W lost in the converter (including the resistance of the inductor and of other passive components). Most of this power is burnt by FEAST itself and needs to be transferred to the cooling system efficiently. The chosen qfn32 package has an exposed cooling pad to which the IC is directly attached, and the pad must be soldered to the gnd plane of the PCB which itself must have a good thermal contact to the cooling system.

Operation at small output current

The size of the power transistors has been chosen for optimum efficiency in the output current range of 1.5-2.5A. For small output currents the excessive size of the transistors induces a large penalty in efficiency, since their large gate capacitance has to be charged at every switching cycle (large driving losses). To partially reduce the losses associated to the large size of the power train, it is possible to stop a fraction of the drivers by pulling down (to gnd) the HalfSw pin. In this way, only 2/5th of the HS and LS transistors are switching, increasing their effective on-resistance (not too relevant for small load currents) but saving switching power. This is power

efficient at small loads, up to about 800mA, as shown in the table below referring to Vin=10V, Vout=2.5V, f=1.8MHz, L=460nH.

	Efficiency (%)			
Iout (mA)	HalfSw floating	HalfSw grounded		
100	39.3%	44.6%		
200	56.5%	61.0%		
300	64.6%	68.1%		
400	69.9%	73.0%		
500	73.7%	75.8%		
600	76.8%	77.7%		
700	78.5%	79.4%		
800	79.6%	80.1%		
900	80.2%	80.4%		
1000	80.8%	80.4%		

Radiation tolerance

The full development of FEAST has been driven by the radiation tolerance goal of reliable flawless operation in the HEP experiments at the CERN Large Hadron Collider (LHC). In particular, radiation tolerance specifications for applications in phase1 upgrades of the LHC include TID up to 20Mrad, displacement damage up to 2.5e14 particles/cm² (1MeV nequivalent), no destructive event in a hadron radiation environment (SEB, SEGR), low rate of SET (in particular resets) – precise specification is system dependent.

Radiation tolerance determined in the first place the choice of the CMOS technology used for the design: high-voltage transistors were required not to be sensitive to SEB and SEGR during heavy ion tests up to an LET of 30MeVmg⁻¹cm² (at normal incidence). For the control circuits, Hardness By Design (HBD) techniques have been systematically used to prevent the opening of leakage currents with TID. Results of SEE test campaigns at heavy ion and pulsed laser facilities enabled the measurement of the cross-section and the localization of weak points during the development, and were used to correct the final design.

Full radiation characterization has been done on FEAST prototypes mounted on full DCDC modules of the FEASTMP type. The results of the characterization are reported in the datasheet of the FEASTMP module that can be found in the public web page of the DCDC converter project: http://project-dcdc.web.cern.ch. Please refer to that document for full radiation tolerance results.

Typical operation waveforms

Full characterization of the FEAST ASIC has been done on prototypes mounted on full DCDC modules of the FEASTMP type. The results of the characterization are reported in the datasheet of the FEASTMP module that can be found in the public web page of the DCDC converter project: http://project-dcdc.web.cern.ch. Please refer to that document to find all waveforms for typical operation of the converter.

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Package description

FEAST is packaged in a plastic Quad Flat No-Lead (QFN) package 5.0x5.0x0.9mm in size, with 32 pads and with an exposed pad to be soldered to the PCB for better thermal properties. The package is rated for a chip temperature increase of 27 to 31 °C/W depending on the air flow. The suggested PCB layout for the integration of FEAST is shown in the following figure. The dimension of the signal pads is 0.25x0.5mm and the one of the the central exposed thermal pad is 3.6x3.6mm. All distances are referred to the center of the signal or exposed thermal pads.

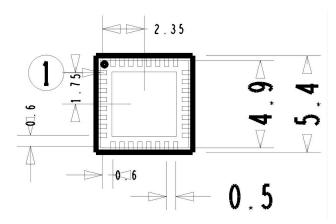


Figure 3: Suggested PCB layout for the integration of the FEAST QFN32 package.

Revision history

Revision	Date	Description
1.0	February2014	First release of the document.